



Product Information Sheet

EPO-TEK® H63

Date: September 2017
Rev: V
No. of Components: Single
Mix Ratio by Weight: N/A
Specific Gravity: 1.79
Pot Life: 28 Days
Shelf Life- Bulk: One year refrigerated

Recommended Cure: 150°C / 1 Hour

Minimum Alternative Cure(s):
May not achieve performance properties listed below
150°C / 30 Minutes
120°C / 1 Hour

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: A single component, electrically insulating, thermally conductive epoxy adhesive for semiconductor, hybrid packaging and electronic circuit assembly applications. It is a higher viscosity alternative to EPO-TEK® H62.

Typical Properties: Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results.
Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	Black		
* Consistency:	Smooth thixotropic paste		
* Viscosity (23°C) @ 10 rpm:	25,000-35,000	cPs	
Thixotropic Index:	1.1		
* Glass Transition Temp:	≥ 120	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expansion (CTE):			
Below Tg:	27	x 10 ⁻⁶ in/in°C	
Above Tg:	125	x 10 ⁻⁶ in/in°C	
Shore D Hardness:	91		
Lap Shear @ 23°C:	1,102	psi	
Die Shear @ 23°C:	≥ 10	Kg	3,556 psi
Degradation Temp:	418	°C	
Weight Loss:			
@ 200°C:	0.05	%	
@ 250°C:	0.19	%	
@ 300°C:	0.66	%	
Suggested Operating Temperature:	< 350	°C (Intermittent)	
Storage Modulus:	466,233	psi	
* Particle Size:	≤ 50	microns	

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity:	0.6	W/mK
Volume Resistivity @ 23°C:	≥ 3 x 10 ¹³	Ohm-cm
Dielectric Constant (1KHz):	4.75	
Dissipation Factor (1KHz):	0.021	

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

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